

PRODUCT ADVISORY

Data Sheet Specification Correction for the Listed Intersil ISL6612E* and ISL6613E* EPSONIC Packaged Products

**Refer to:
PA10062**

Date: June 15, 2010

June 15, 2010

To: Our Valued Intersil Customers

Subject: **Data Sheet Specification Correction for the Listed Intersil ISL6612E* and ISL6613E* EPSONIC Packaged Products**

This advisory is to inform you that Intersil has made corrections to the POD (Package Outline Drawing) referenced in the data sheet specification for the listed Intersil ISL6612E* and ISL6613E* EPSONIC (Exposed Pad Small Outline Integrated Circuit) packaged products. The updates to the POD correct the package body width (“E”) millimeter dimensions and change the controlling dimension from millimeter to inches in Note 10. There have been no changes made to the package or product itself. The updated data sheet incorporating the corrected POD is available on the Intersil web site at <http://www.intersil.com/data/fn/fn9153.pdf>.

Products Affected:

ISL6612ECB-T	ISL6612EIBZ-T	ISL6613ECBZA-TR5169
ISL6612ECBZ	ISL6613ECBZ	ISL6613ECBZR5214
ISL6612ECBZ-T	ISL6613ECBZ-T	ISL6613EIBZ
ISL6612ECBZ-TR5248	ISL6613ECBZ-TR5169	ISL6613EIBZ-T
ISL6612EIBZ	ISL6613ECBZ-TR5214	

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to continue receiving product manufactured to the same conditions used for material supplied today.

If you have concerns with this change notice, Intersil must hear from you immediately. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Jon Brewster

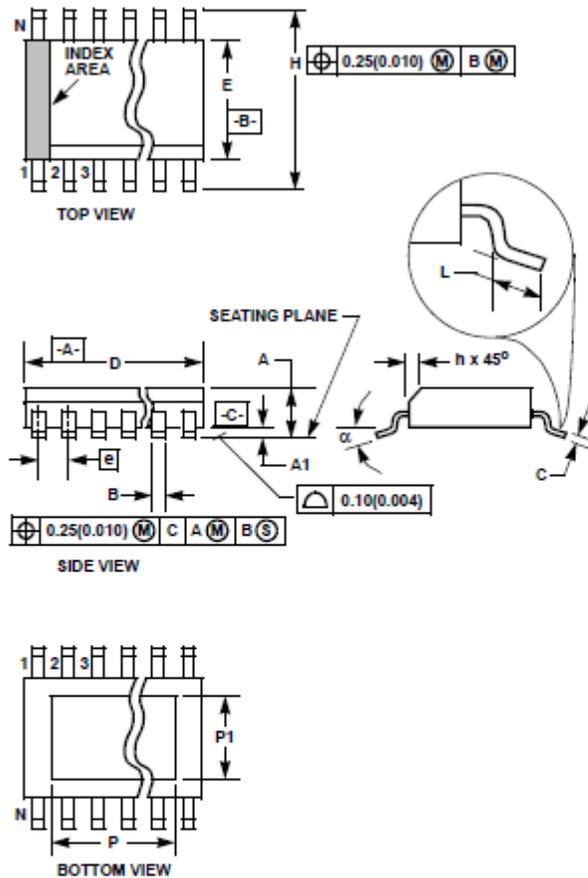
Jon Brewster
Intersil Corporation

PA10062

CC: J. Touvell M. Driscoll J. Day

Incorrect POD – PA10062

Small Outline Exposed Pad Plastic Packages (EPSOIC)



M8.15B
8 LEAD NARROW BODY SMALL OUTLINE EXPOSED PAD PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.056	0.066	1.43	1.68	-
A1	0.001	0.005	0.03	0.13	-
B	0.0138	0.0192	0.35	0.49	9
C	0.0075	0.0098	0.19	0.25	-
D	0.189	0.196	4.80	4.98	3
E	0.150	0.157	3.81	3.99	4
e	0.050 BSC		1.27 BSC		-
H	0.230	0.244	5.84	6.20	-
h	0.010	0.016	0.25	0.41	5
L	0.016	0.035	0.41	0.64	6
N	8		8		7
α	0°	8°	0°	8°	-
P	-	0.094	-	2.387	11
P1	-	0.094	-	2.387	11

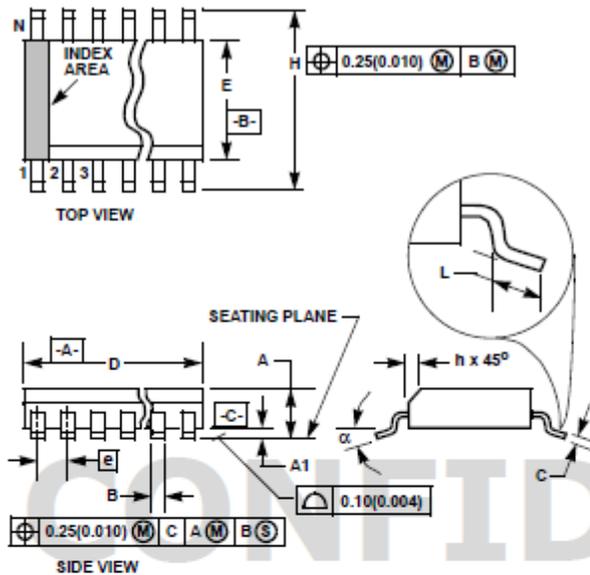
Rev. 3 6/05

NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
11. Dimensions "P" and "P1" are thermal and/or electrical enhanced variations. Values shown are maximum size of exposed pad within lead count and body size.

Correct POD – PA10062

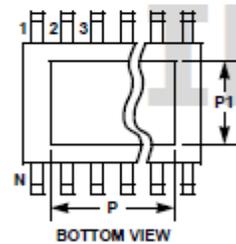
Small Outline Exposed Pad Plastic Packages (EPSONIC)



M8.15B
8 LEAD NARROW BODY SMALL OUTLINE EXPOSED PAD
PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.056	0.066	1.43	1.68	-
A1	0.001	0.005	0.03	0.13	-
B	0.0138	0.0192	0.35	0.49	9
C	0.0075	0.0098	0.19	0.25	-
D	0.189	0.196	4.80	4.98	3
E	0.150	0.157	3.81	3.99	4
e	0.050 BSC		1.27 BSC		-
H	0.230	0.244	5.84	6.20	-
h	0.010	0.016	0.25	0.41	5
L	0.016	0.035	0.41	0.64	6
N	8		8		7
alpha	0°	8°	0°	8°	-
P	-	0.094	-	2.387	11
P1	-	0.094	-	2.387	11

Rev. 4 1/09



NOTES:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- "L" is the length of terminal for soldering to a substrate.
- "N" is the number of terminal positions.
- Terminal numbers are shown for reference only.
- The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
- Controlling dimension: INCH. Converted millimeter dimensions are not necessarily exact.
- Dimensions "P" and "P1" are thermal and/or electrical enhanced variations. Values shown are maximum size of exposed pad within lead count and body size.